8-Bit Serial-Input/Serial or Parallel-Output Shift Register with Latched 3-State Outputs

High-Performance Silicon-Gate CMOS

The MC74HC595A consists of an 8-bit shift register and an 8-bit D-type latch with three-state parallel outputs. The shift register accepts serial data and provides a serial output. The shift register also provides parallel data to the 8-bit latch. The shift register and latch have independent clock inputs. This device also has an asynchronous reset for the shift register.

The HC595A directly interfaces with the SPI serial data port on CMOS MPUs and MCUs.

Features

- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7 A
- Chip Complexity: 328 FETs or 82 Equivalent Gates
- Improvements over HC595
 - Improved Propagation Delays
 - 50% Lower Quiescent Power
 - Improved Input Noise and Latchup Immunity
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

1



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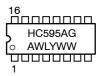
MARKING DIAGRAMS



PDIP-16 N SUFFIX CASE 648 16 **ከሰሰሰሰሰሰሰ** MC74HC595AN O AWLYYWWG ሁሁሁሁ

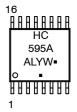


SOIC-16 D SUFFIX CASE 751B





TSSOP-16 DT SUFFIX CASE 948F



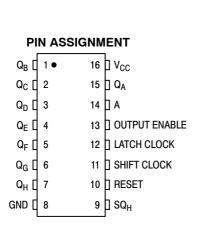
A = Assembly Location

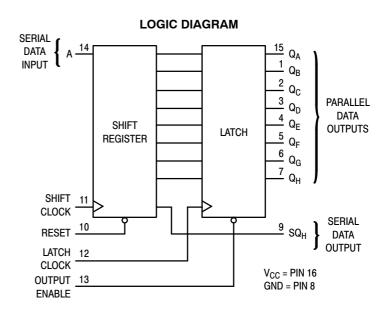
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G, • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.





ORDERING INFORMATION

Device	Package	Shipping [†]	
MC74HC595ANG	PDIP-16 (Pb-Free)	500 Units / Rail	
MC74HC595ADG	SOIC-16	40 Heile / Beil	
NLV74HC595ADG* (Pb-Free)		48 Units / Rail	
MC74HC595ADR2G	SOIC-16		
NLV74HC595ADR2G*	(Pb-Free)	0500 Tana 9 Dayl	
MC74HC595ADTR2G	TSSOP-16	2500 Tape & Reel	
NLV74HC595ADTR2G*	(Pb-Free)		
MC74HC595ADTG	TSSOP-16 (Pb-Free)	96 Units / Tube	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
l _{in}	DC Input Current, per Pin	±20	mA
l _{out}	DC Output Current, per Pin	±35	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±75	mA
P _D	Power Dissipation in Still Air, Plastic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
T _{stg}	Storage Temperature	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package)	260	°C
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	>3000 >400 N/A	V

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C SOIC Package: – 7 mW/°C from 65° to 125°C

TSSOP Package: - 6.1 mW/°C from 65° to 125°C 1. Tested to EIA/JESD22–A114–A.

2. Tested to EIA/JESD22-A115-A.

3. Tested to JESD22-C101-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	٧	
T _A	Operating Temperature, All Package Types		– 55	+ 125	°C
t _r , t _f	Input Rise and Fall Time V_{CC} = (Figure 1) V_{CC} = V_{CC} =	0 0 0	1000 500 400	ns	

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

			V _{CC}	Guar	anteed Lim	it	
Symbol	Parameter	Test Conditions	v	– 55 to 25°C	≤ 85 °C	≤ 125°C	Unit
V _{IH}	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V _{IL}	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V _{OH}	Minimum High-Level Output Voltage, Q _A - Q _H	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \ \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$\label{eq:Vin} \begin{aligned} V_{in} = V_{IH} \text{ or } V_{IL} & & I_{out} \leq 2.4 \text{ mA} \\ & I_{out} \leq 6.0 \text{ mA} \\ & I_{out} \leq 7.8 \text{ mA} \end{aligned}$	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.2 3.7 5.2	

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

			V _{CC}	Guar	anteed Lim	it	
Symbol	Parameter	Test Conditions		– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
V _{OL}	Maximum Low-Level Output Voltage, Q _A – Q _H	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \ \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		I _{out} ≤	≤ 2.4 mA 3.0 ≤ 6.0 mA 4.5 ≤ 7.8 mA 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.4 0.4 0.4	
V _{OH}	Minimum High-Level Output Voltage, SQ _H	$V_{in} = V_{IH} \text{ or } V_{IL}$ $II_{out}I \leq 20 \mu A$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		II _{out} I :	≤ 2.4 mA 3.0 ≤ 4.0 mA 4.5 ≤ 5.2 mA 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.2 3.7 5.2	
V _{OL}	Maximum Low-Level Output Voltage, SQ _H	$V_{in} = V_{IH} \text{ or } V_{IL}$ $II_{out}I \leq 20 \mu A$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		ll _{out} l .	≤ 2.4 mA 3.0 ≤ 4.0 mA 4.5 ≤ 5.2 mA 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.4 0.4 0.4	
l _{in}	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or GND	6.0	± 0.1	± 1.0	± 1.0	μА
l _{OZ}	Maximum Three–State Leakage Current, Q _A – Q _H	Output in High-Impedance $V_{in} = V_{IL}$ or V_{IH} $V_{out} = V_{CC}$ or GND	e State 6.0	± 0.5	± 5.0	± 10	μΑ
I _{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	6.0	4.0	40	160	μΑ

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6.0 ns)

		V _{CC}	Guar	anteed Lim	it	
Symbol	Parameter	v	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
f _{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 7)	2.0 3.0 4.5 6.0	6.0 15 30 35	4.8 10 24 28	4.0 8.0 20 24	MHz
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Shift Clock to SQ _H (Figures 1 and 7)	2.0 3.0 4.5 6.0	140 100 28 24	175 125 35 30	210 150 42 36	ns
t _{PHL}	Maximum Propagation Delay, Reset to SQ _H (Figures 2 and 7)	2.0 3.0 4.5 6.0	145 100 29 25	180 125 36 31	220 150 44 38	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Latch Clock to \mathbf{Q}_{A} – \mathbf{Q}_{H} (Figures 3 and 7)	2.0 3.0 4.5 6.0	140 100 28 24	175 125 35 30	210 150 42 36	ns
t _{PLZ} , t _{PHZ}	Maximum Propagation Delay, Output Enable to ${\sf Q}_{\sf A}$ – ${\sf Q}_{\sf H}$ (Figures 4 and 8)	2.0 3.0 4.5 6.0	150 100 30 26	190 125 38 33	225 150 45 38	ns
t _{PZL} , t _{PZH}	Maximum Propagation Delay, Output Enable to Q _A – Q _H (Figures 4 and 8)	2.0 3.0 4.5 6.0	135 90 27 23	170 110 34 29	205 130 41 35	ns

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6.0 \text{ ns}$)

		Vcc	V _{CC} Guaranteed Limit			
Symbol	Parameter	v	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t _{TLH} , t _{THL}	Maximum Output Transition Time, Q _A – Q _H (Figures 3 and 7)	2.0 3.0 4.5 6.0	60 23 12 10	75 27 15 13	90 31 18 15	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, SQ _H (Figures 1 and 7)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 16	110 36 22 19	ns
C _{in}	Maximum Input Capacitance	_	10	10	10	pF
C _{out}	Maximum Three-State Output Capacitance (Output in High-Impedance State), Q _A - Q _H	_	15	15	15	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Package)*	300	pF

TIMING REQUIREMENTS (Input $t_r = t_f = 6.0 \text{ ns}$)

		V _{CC}	Guara	anteed Limi	t	
Symbol	Parameter	V	25°C to -55°C	≤ 85 °C	≤ 125°C	Unit
t _{su}	Minimum Setup Time, Serial Data Input A to Shift Clock	2.0	50	65	75	ns
	(Figure 5)	3.0	40	50	60	
		4.5	10	13	15	
		6.0	9.0	11	13	
t _{su}	Minimum Setup Time, Shift Clock to Latch Clock	2.0	75	95	110	ns
	(Figure 6)	3.0	60	70	80	
		4.5	15	19	22	
		6.0	13	16	19	
t _h	Minimum Hold Time, Shift Clock to Serial Data Input A	2.0	5.0	5.0	5.0	ns
• •	(Figure 5)	3.0	5.0	5.0	5.0	
		4.5	5.0	5.0	5.0	
		6.0	5.0	5.0	5.0	
t _{rec}	Minimum Recovery Time, Reset Inactive to Shift Clock	2.0	50	65	75	ns
	(Figure 2)	3.0	40	50	60	
		4.5	10	13	15	
		6.0	9.0	11	13	
t _w	Minimum Pulse Width, Reset	2.0	60	75	90	ns
	(Figure 2)	3.0	45	60	70	
		4.5	12	15	18	
		6.0	10	13	15	
t _w	Minimum Pulse Width, Shift Clock	2.0	50	65	75	ns
	(Figure 1)	3.0	40	50	60	
		4.5	10	13	15	
		6.0	9.0	11	13	
t _w	Minimum Pulse Width, Latch Clock	2.0	50	65	75	ns
	(Figure 6)	3.0	40	50	60	
		4.5	10	13	15	
		6.0	9.0	11	13	
t _r , t _f	Maximum Input Rise and Fall Times	2.0	1000	1000	1000	ns
	(Figure 1)	3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

FUNCTION TABLE

Inputs							Resulting F	unction	
Operation	Reset	Serial Input A	Shift Clock	Latch Clock	Output Enable	Shift Register Contents	Latch Register Contents	Serial Output SQ _H	Parallel Outputs Q _A – Q _H
Reset shift register	L	Х	Х	L, H, ↓	L	L	U	L	U
Shift data into shift register	Н	D	1	L, H, ↓	L	$\begin{array}{c} \text{D} \rightarrow \text{SR}_{A};\\ \text{SR}_{N} \rightarrow \text{SR}_{N+1} \end{array}$	U	$SR_G \rightarrow SR_H$	U
Shift register remains unchanged	Н	Х	L, H, ↓	L, H, ↓	L	U	U	U	U
Transfer shift register contents to latch register	Н	Х	L, H, ↓	1	L	U	$SR_N \rightarrow LR_N$	U	SR _N
Latch register remains unchanged	Х	Х	Х	L, H, ↓	L	*	U	*	U
Enable parallel outputs	Х	Х	Х	Х	L	*	**	*	Enabled
Force outputs into high impedance state	Х	Х	Х	Х	Н	*	**	*	Z

SR = shift register contents

D = data (L, H) logic level

↑ = Low-to-High

* = depends on Reset and Shift Clock inputs

PIN DESCRIPTIONS

INPUTS A (Pin 14)

Serial Data Input. The data on this pin is shifted into the 8-bit serial shift register.

CONTROL INPUTSShift Clock (Pin 11)

Shift Register Clock Input. A low-to-high transition on this input causes the data at the Serial Input pin to be shifted into the 8-bit shift register.

Reset (Pin 10)

Active-low, Asynchronous, Shift Register Reset Input. A low on this pin resets the shift register portion of this device only. The 8-bit latch is not affected.

Latch Clock (Pin 12)

Storage Latch Clock Input. A low-to-high transition on this input latches the shift register data.

Output Enable (Pin 13)

Active–low Output Enable. A low on this input allows the data from the latches to be presented at the outputs. A high on this input forces the outputs (Q_A-Q_H) into the high–impedance state. The serial output is not affected by this control unit.

OUTPUTS

Q_A - Q_H (Pins 15, 1, 2, 3, 4, 5, 6, 7)

Noninverted, 3-state, latch outputs.

SQ_H (Pin 9)

Noninverted, Serial Data Output. This is the output of the eighth stage of the 8-bit shift register. This output does not have three-state capability.

LR = latch register contents U = remains unchanged

 $[\]downarrow$ = High-to-Low

^{** =} depends on Latch Clock input

SWITCHING WAVEFORMS

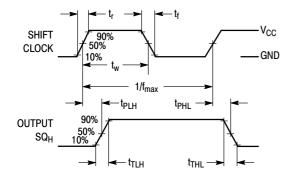


Figure 1.

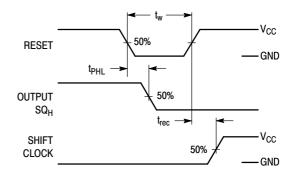


Figure 2.

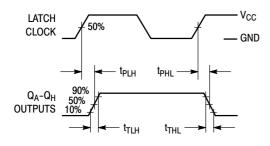


Figure 3.

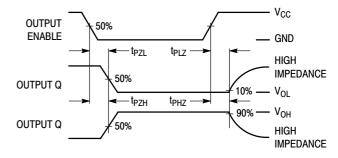


Figure 4.

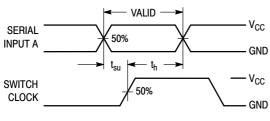


Figure 5.

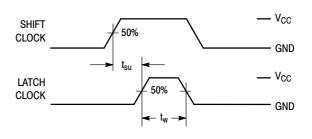
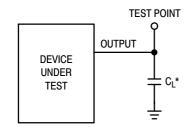


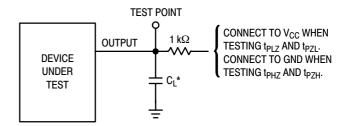
Figure 6.

TEST CIRCUITS



*Includes all probe and jig capacitance

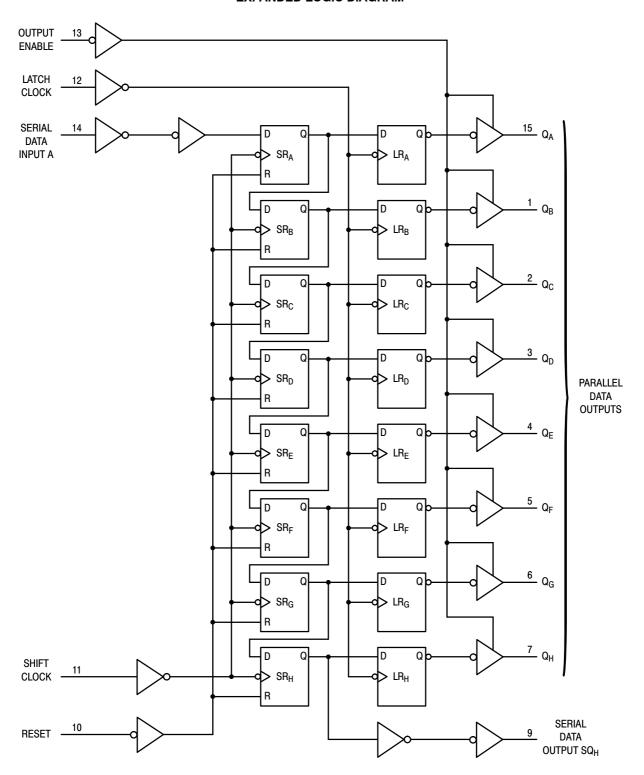
Figure 7.



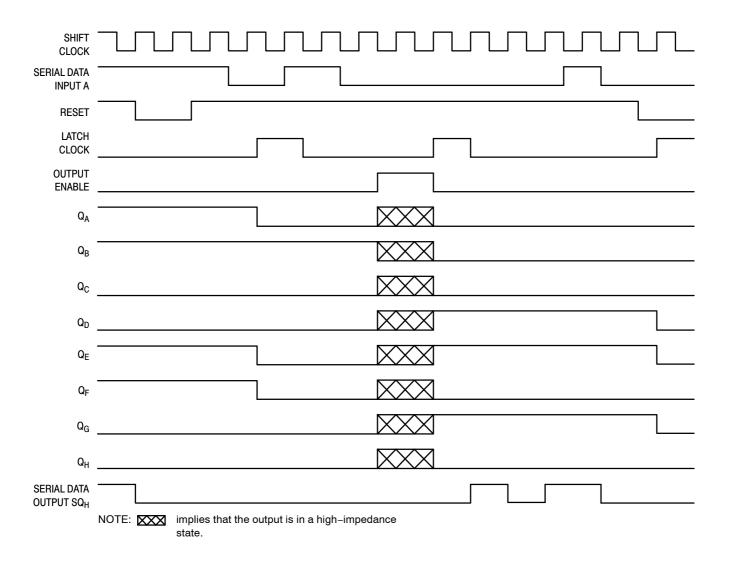
*Includes all probe and jig capacitance

Figure 8.

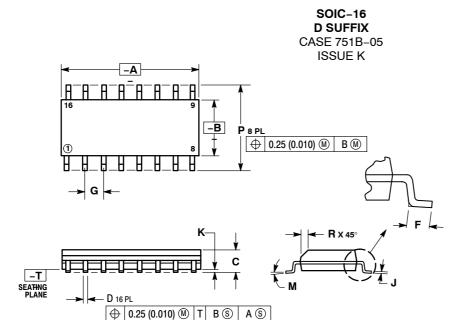
EXPANDED LOGIC DIAGRAM



TIMING DIAGRAM



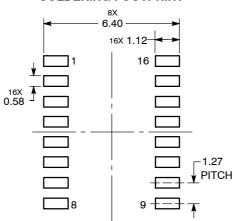
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

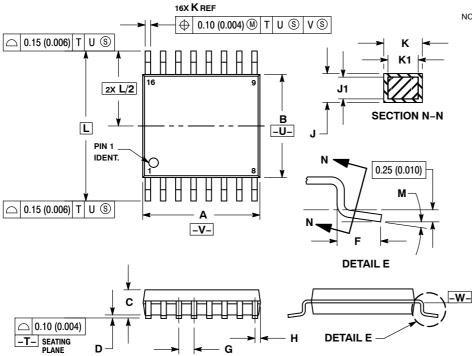
	MILLIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.2	7 BSC	0.05	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

TSSOP-16 CASE 948F-01 **ISSUE B**



NOTES:

- OTES:

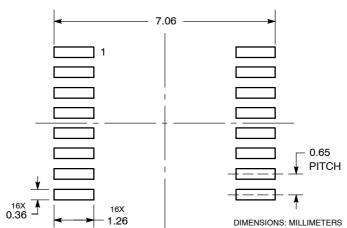
 1. DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD
 FLASH. PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

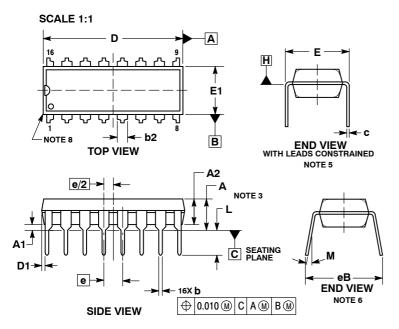
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
C		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026	BSC	
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
Κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
М	0°	8°	0 °	8°	

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 **ISSUE U**



NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCHES
- DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACK-AGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
 DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH
- OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
- DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
- DIMENSION E3 IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE
- CORNERS).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α		0.210		5.33
A1	0.015		0.38	
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
С	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005		0.13	
Е	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100 BSC		2.54 BSC	
eВ		0.430		10.92
L	0.115	0.150	2.92	3.81
М		10°		10°

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